

**IN THE CLAIMS:**

1. (original) A Hop-FED structure comprising:
  - a. a substrate;
  - b. emitter areas on said substrate;
  - c. a hop-plate disposed over said substrate and emitter areas with a surface of the hop-plate opposing said substrate and emitter areas; and
  - d. an electrically conductive layer formed on said surface of the hop-plate.
2. (original) A Hop-FED structure according to claim 1, wherein said surface is formed with projections that space the remainder of the hop-plate from said substrate and emitter areas.
3. (original) A Hop-FED structure according to claim 2, wherein said projections are formed as pillars or ribs.
4. (currently amended) A Hop-FED structure according to claim 2 ~~or 3~~, wherein said electrically conductive layer is provided on said projections.

5. (currently amended) A Hop-FED structure according to claim 2 or 3, wherein said electrically conductive layer is not provided on said projections.
6. (currently amended) A Hop-FED structure according to claim 1 any of the preceding claims, wherein said electrically conductive layer is of a material of high electrical resistivity.
7. (original) A Hop-FED structure according to claim 6, wherein said material has a surface resistivity in the range  $10^7$  to  $10^{11}$  ohms per square.
8. (original) A Hop-FED structure according to claim 7, wherein said material has a surface resistivity in the range  $10^8$  to  $10^{10}$  ohms per square.
9. (original) A Hop-FED structure according to claim 8, wherein said material has a surface resistivity of substantially  $10^9$  ohms per square.
10. (currently amended) A Hop-FED structure according to claim 6, 7, 8 or 9, wherein said material is selected from the group comprising amorphous silicon and silver doped silica.
11. (currently amended) A Hop-FED structure according to claim 1 any of the preceding claims, wherein said electrically conductive layer extends partially within the channels of the hop-plate.
12. (currently amended) A Hop-FED structure according to claim 1 any of the preceding claims, wherein said electrically conductive layer is connected to means for holding said layer at a predetermined potential.
13. (cancelled)
14. (original) A Hop-FED structure comprising:
  - a. a cathode with emitter areas;
  - b. an anode arranged to receive electrons emitted from the cathode;
  - c. a hop-plate disposed between the cathode and anode;
  - d. spacer means arranged to provide a space between said cathode and anode; and

- e. gettering material disposed in said space.
15. (original) A Hop-FED structure according to claim 14, wherein said spacer means comprises projections provided on one or both faces of said hop-plate.
16. (currently amended) A Hop-FED structure according to claim 14 ~~or 15~~, further comprising a flue-plate between said hop-plate and anode.
17. (original) A Hop-FED structure according to claim 16, wherein said spacer means comprises projections provided on one or both faces of said flue-plate.
18. (currently amended) A Hop-FED structure according to claim 15~~or 17~~, wherein said spacer means are formed as pillars or ribs on said hop-plate and/or flue-plate.
19. (currently amended) A Hop-FED structure according to claim 14 any of claims 14 to 18, wherein said gettering material forms a distributed getter.
20. (currently amended) A Hop-FED structure according to claim 14 any of claims 14 to 19, wherein said gettering material comprises a non-evaporated getter.
21. (original) A Hop-FED structure according to claim 20, wherein said gettering material comprises an alloy containing at least one Group IV metal.
22. (cancelled)
23. (currently amended) A Hop-FED structure according to claim 14 any of claims 14 to 22, wherein the structure is sealed by a glass-frit seal that is spaced from said gettering material, and the structure further comprises a conductive member that is compatible with said glass-frit and extends from outside the structure, through said glass-frit seal and to said gettering material, to which it is electrically connected.
- 24 - 43. (cancelled)

44. (original) A Hop-FED structure comprising:

- a. a cathode having a substrate and emitter areas on said substrate;
- b. an anode arranged to receive electrons emitted from the cathode;
- c. a hop-plate disposed over said substrate and emitter areas, between the cathode and anode, with a surface of the hop-plate opposing said substrate and emitter areas;
- d. an electrically conductive layer formed on said surface of the hop-plate.
- e. spacer means arranged to provide a space between said cathode and anode; and
- f. gettering material disposed in said space.